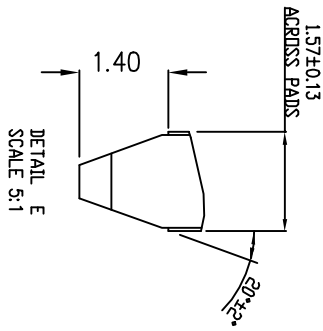


| | | | | | | | | | | | | | |
|-------------|----------|-----|---------|--|--|------------------------------------|--|------------------|--|--|--|--|--|
| mat'l. code | | | | tolerances unless otherwise specified | | | | CUSTOMER COPY | | <div><div>A</div><div>FCI</div><div>www.fciconnect.com</div></div> | | | |
| itr | ecn no | dr | ddte | linear | | X ± .38 .XX ± .25 .XXX ± .10 | | projection | | title PCI-E 200P CARD EDGE | | | |
| | | | | | | | | | | | | | |
| A | T06-0079 | J/H | 4/14/06 | angles | | 0° ± 2° | | | | | | | |
| | | | | dr | | JASON HSU 4/14/06 | | MM | | product family PCI | | | |
| | | | | engr | | JASON HSU 4/14/06 | | ← | | Size dng no | | | |
| | | | | chr | | STERLING LIN 4/14/06 | | scale | | | | | |
| | | | | appd | | HC UDU 4/14/06 | | N/A | | A4 10054652 | | | |
| sheet | revision | A | A | A | | A | | | | | | | |
| index | sheet | 1 | 2 | 3 | | 4 | | | | | | | |

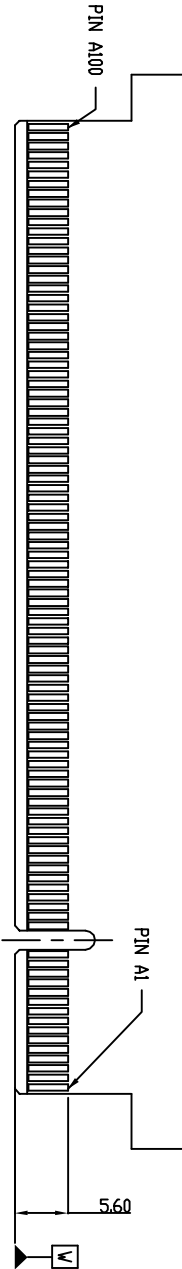
ACAD

B

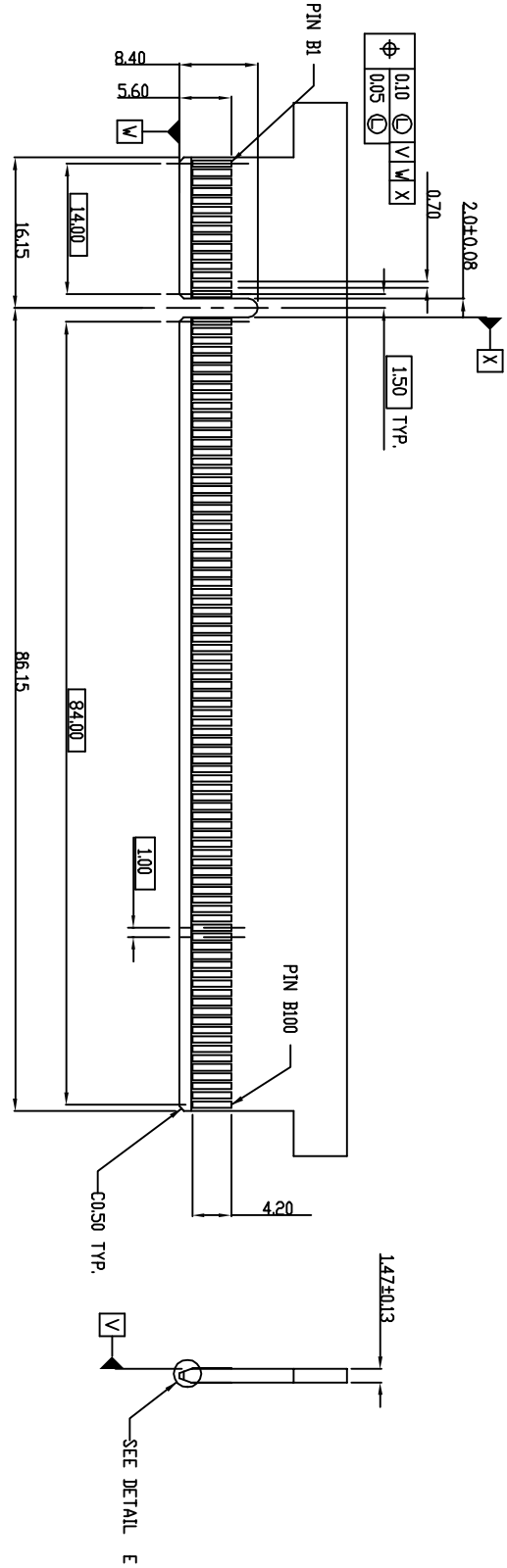
A



→ I/O PANEL DIRECTION
SECONDARY (SOLDER) SIDE



→ I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE



ACAD

| mat'l. code | tr | ecn no | dr | date | tolerances unless otherwise specified | CUSTOMER COPY | title | product family | code |
|-------------|----------|--------|----|------|---------------------------------------|---------------|----------------------|----------------|------|
| A | | | | | .XX ±.25 .XXX ±.10 0° ±2° | projection | PCI-E 200P CARD EDGE | PCI | — |
| | | | | | engr JASON HSU 4/14/06 | MM | | | |
| | | | | | chr STERLING LIN 4/14/06 | | | | |
| | | | | | appd HC LIU 4/14/06 | scale | | | |
| | | | | | | N/A | | | |
| sheet | revision | | | | | | | | |
| index | sheet | | | | | | | | |

code
22526



1 | 2

3 |

4

NOTES:
1.MATERIAL:
HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0,
COLOR IN BLACK.
CONTACTS: COPPER ALLOY.

2.FINISH:
CONTACTS: GOLD PLATING ON CONTACT AREA,
100 u"MIN. TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50u"MIN. NICKEL UNDERPLATING OVER ALL.
BOARD LOCKS: 100 u" TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50u"MIN. NICKEL UNDERPLATING OVER ALL.

3. DURABILITY: 50 CYCLES.
4. ROHS COMPATIBLE PRODUCT SPECIFICATIONS
a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 25um min. MATTE PURE TIN OVER 1,27um MIN. NICKEL UNDERPLATE.
b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C+5C° SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1,60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE
10054652 - X X X X X X X LF

LEAD FREE

PACKAGING OPTIONS
T-TRAY PACKAGING

RESERVE
0

TAIL LENGTH OPTIONS

| | DIM "D" | SUGGESTED PCB THICKNESS |
|---|---------|-------------------------|
| 1 | 3.10 | 2.36±0.10 |
| 2 | 2.54 | 1.56±0.10 |

TERMINAL PLATING OPTIONS
0-50u" NI UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA -----COMPATIBLE ROHS
1-50u" NI UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA -----COMPATIBLE ROHS
2-50u" NI UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA -----COMPATIBLE ROHS

| mat'l. code | | | | tolerances unless otherwise specified | | | | CUSTOMER COPY | | A FCI | | www.fciconnect.com | |
|-------------|----------|----|------|---------------------------------------|--------------|------------|-------|----------------------|----------------|-------|------|--------------------|--|
| ltr | ecn no | dr | date | linear | .XX ±.25 | projection | MM | title | product family | PCI | code | sheet | |
| A | | | | .XXX ±.10 | 0" ±.2" | | | PCI-E 200P CARD EDGE | | | | 4 of 4 | |
| | | | | engr | JASON HSU | 4/14/06 | | | | | | | |
| | | | | chrt | STERLING LIN | 4/14/06 | scale | | | | | | |
| | | | | appd | HC LOU | 4/14/06 | N/A | | | | | | |
| sheet | revision | | | | | | | | | | | | |
| index | sheet | | | | | | | | | | | | |

1 | 2

3 |

4

ACAD

code code
22526